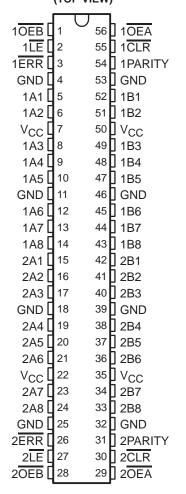
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- Members of the Texas Instruments
  Widebus™ Family
- State-of-the-Art EPIC-IIB™ BiCMOS Design Significantly Reduces Power Dissipation
- Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17
- Typical V<sub>OLP</sub> (Output Ground Bounce) < 1 V at V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25°C
- Distributed V<sub>CC</sub> and GND Pin Configuration Minimizes High-Speed Switching Noise
- Flow-Through Architecture Optimizes PCB Layout
- High-Drive Outputs (–32-mA I<sub>OH</sub>, 64-mA I<sub>OL</sub>)
- Parity-Error Flag With Parity Generator/Checker
- Latch for Storage of the Parity-Error Flag
- Package Options Include Plastic 300-mil Shrink Small-Outline (DL) and Thin Shrink Small-Outline (DGG) Packages and 380-mil Fine-Pitch Ceramic Flat (WD) Package Using 25-mil Center-to-Center Spacings

#### description

The 'ABT16853 dual 8-bit to 9-bit parity transceivers are designed for communication between data buses. When data is transmitted from the A bus to the B bus, a parity bit is generated. When data is transmitted from the B bus to the A bus, with its corresponding parity bit, the open-collector parity-error (ERR) output indicates whether or not an error in the B data has occurred. The output-enable (OEA and OEB) inputs can be used to disable the device so that the buses are effectively isolated. The 'ABT16853 provide true data at the outputs.

SN54ABT16853 . . . WD PACKAGE SN74ABT16853 . . . DGG OR DL PACKAGE (TOP VIEW)



A 9-bit parity generator/checker generates a parity-odd (PARITY) output and monitors the parity of the I/O ports with the  $\overline{ERR}$  flag. The parity-error output can be passed, sampled, stored, or cleared from the latch using the latch-enable ( $\overline{LE}$ ) and clear ( $\overline{CLR}$ ) control inputs. When both  $\overline{OEA}$  and  $\overline{OEB}$  are low, data is transferred from the A bus to the B bus, and inverted parity is generated. Inverted parity is a forced error condition that gives the designer more system diagnostic capability.

To ensure the high-impedance state during power up or power down,  $\overline{OE}$  should be tied to  $V_{CC}$  through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.



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# SN54ABT16853, SN74ABT16853 DUAL 8-BIT TO 9-BIT PARITY BUS TRANSCEIVERS

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## description (continued)

The SN54ABT16853 is characterized for operation over the full military temperature range of  $-55^{\circ}$ C to  $125^{\circ}$ C. The SN74ABT16853 is characterized for operation from  $-40^{\circ}$ C to  $85^{\circ}$ C.

#### **FUNCTION TABLE**

		II.	NPUTS				OUTPU	JT AND I/O						
OEB	OEA	CLR	LE	AI Σ OF H	BI <sup>†</sup> Σ OF H	Α	В	PARITY	ERR‡	FUNCTION				
L	Н	Х	Х	Odd Even	NA	NA	Α	L H	NA	A data to B bus and generate parity				
Н	L	Х	L	NA	Odd Even	В	NA	NA	H L	B data to A bus and check parity				
Н	L	Н	Н	NA	Х	Χ	NA	NA	NC	Store error flag				
Х	Χ	L	Н	Х	Х	Х	NA	NA	Н	Clear error-flag register				
		Н	Н	Х					NC					
н	Н	L	Н	Χ	Х	7	Z	Z	Н	Isolation§				
"	П	X	L	L Odd	^		2 2	2	۷	2	۷	۷	Н	(parity check)
		X	L	H Even					L					
L	L	Х	Х	Odd Even	NA	NA	Α	H L	NA	A data to B bus and generate inverted parity				

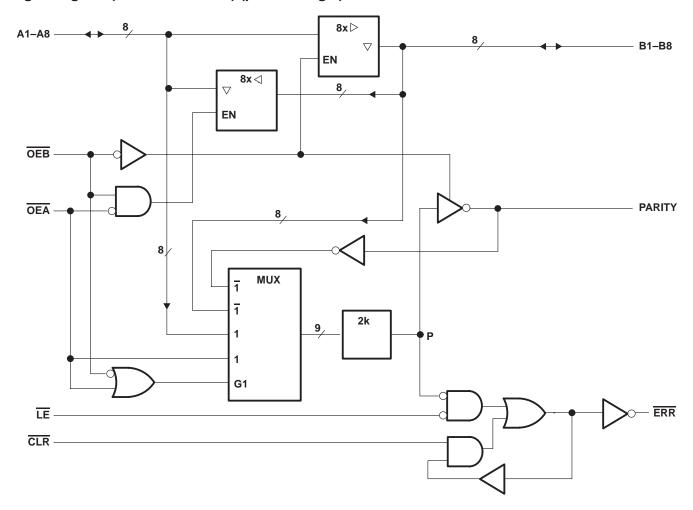
NA = not applicable, NC = no change, X = don't care

<sup>†</sup> Summation of high-level inputs includes PARITY along with Bi inputs.

<sup>‡</sup>Output states shown assume ERR was previously high.

<sup>§</sup> In this mode, ERR (when clocked) shows inverted parity of the A bus.

# logic diagram (each transceiver) (positive logic)



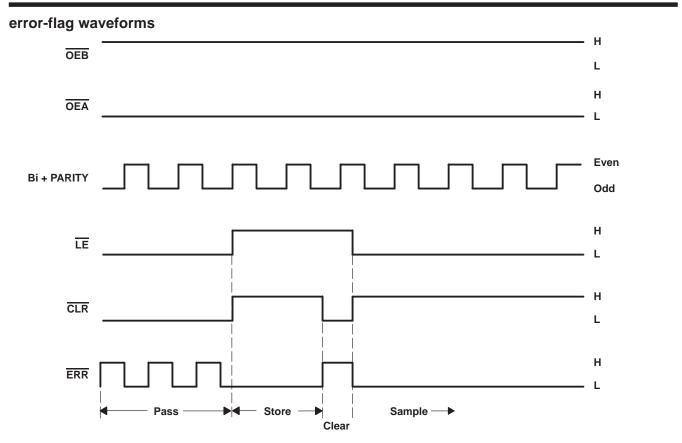
### **ERROR-FLAG FUNCTION TABLE**

INPU	JTS	INTERNAL TO DEVICE	OILI PILL I		FUNCTION
CLR	LE	POINT P	ERR <sub>n-1</sub> †	ERR	
		L	Х	L	Pass
		Н	^	Н	Pass
		L	Χ	L	
Н	L	Х	L	L	Sample
		Н	Н	Н	
L	Н	Х	Х	Н	Clear
н	Н	Х	L	L	Store
	П	^	Н	Н	Store

<sup>†</sup>State of ERR before changes at CLR, LE, or point P

# SN54ABT16853, SN74ABT16853 **DUAL 8-BIT TO 9-BIT PARITY BUS TRANSCEIVERS**

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# absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V <sub>CC</sub>	0.5 V to 7 V
Input voltage range, V <sub>I</sub> (except I/O ports) (see Note 1)	0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, VO	–0.5 V to 5.5 V
Current into any output in the low state, IO: SN54ABT16853	96 mA
SN74ABT16853	128 mA
Input clamp current, I <sub>IK</sub> (V <sub>I</sub> < 0)	–18 mA
Output clamp current, I <sub>OK</sub> (V <sub>O</sub> < 0)	–50 mA
Package thermal impedance, θ <sub>JA</sub> (see Note 2): DGG package	81°C/W
DL package	74°C/W
Storage temperature range, T <sub>stg</sub>	–65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

2. The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51.



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## recommended operating conditions (see Note 3)

			SN54ABT	16853	SN74ABT	16853	UNIT
			MIN	MAX	MIN	MAX	UNIT
VCC	Supply voltage		4.5	5.5	4.5	5.5	V
VIH	High-level input voltage		2	N	2		V
VIL	Low-level input voltage			0.8		0.8	V
VI	Input voltage		0 4	Vcc	0	VCC	V
Vон	High-level output voltage	ERR	4	5.5		5.5	V
ІОН	High-level output current	Except ERR	770	-24		-32	mA
loL	Low-level output current		0	48		64	mA
Δt/Δν	Input transition rise or fall rate	Outputs enabled	Q	10		10	ns/V
T <sub>A</sub>	Operating free-air temperature		<b>–</b> 55	125	-40	85	°C

NOTE 3: Unused pins (input or I/O) must be held high or low to prevent them from floating.

## electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	DAMETED	TEST COL	UDITIONS	Т	A = 25°C	;	SN54AB	Γ16853	SN74AB1	16853	UNIT	
PA	RAMETER	TEST COI	SNOTTIONS	MIN	TYP†	MAX	MIN	MAX	MIN	MAX	UNII	
VIK		$V_{CC} = 4.5 \text{ V},$	I <sub>I</sub> = -18 mA			-1.2		-1.2		-1.2	V	
		$V_{CC} = 4.5 \text{ V},$	$I_{OH} = -3 \text{ mA}$	2.5	3		2.5					
Vон	All outputs	$V_{CC} = 5 V$ ,	I <sub>OH</sub> = -3 mA	3	3.4		3		3		V	
VOH	except ERR	V <sub>CC</sub> = 4.5 V	$I_{OH} = -24 \text{ mA}$				2				V	
		VCC = 4.5 V	$I_{OH} = -32 \text{ mA}$	2*	2.7				2			
VOL		V <sub>CC</sub> = 4.5 V	$I_{OL} = 24 \text{ mA}$		0.25	0.55		0.55			V	
VOL		VCC = 4.5 V	$I_{OL} = 64 \text{ mA}$		0.3	0.55*				0.55	V	
$V_{hys}$					100						mV	
IOH	ERR	$V_{CC} = 4.5 \text{ V},$	V <sub>OH</sub> = 5.5 V			20		20		20	μΑ	
l <sub>off</sub>		$V_{CC} = 0$ ,	$V_I$ or $V_O \le 4.5 \text{ V}$			±100		3E1		±100	μΑ	
ICEX	Outputs high	$V_{CC} = 5.5 \text{ V},$	V <sub>O</sub> = 5.5 V			50		50		50	μΑ	
١	Control inputs	V00 - 5 5 V VI - V	loo or GND			±1	S	±1		±1		
li l	A or B ports	V <sub>CC</sub> = 5.5 V, V <sub>I</sub> = V	CC or GMD			±100	90	±100		±100	μΑ	
I <sub>IL</sub>	A or B ports	$V_{CC} = 0$ ,	$V_I = GND$			-50	Q'Q	<b>-</b> 50		-50	μΑ	
10 <sup>‡</sup>		$V_{CC} = 5.5 \text{ V},$	V <sub>O</sub> = 2.5 V	-50	-100	-180	-50	-180	-50	-180	mA	
IOZH§		V <sub>CC</sub> =5.5 V,	$V_0 = 2.7 \text{ V}$			50		50		50	μΑ	
IOZL§		$V_{CC} = 5.5 \text{ V},$	V <sub>O</sub> = 0.5 V			-50		-50		-50	μΑ	
		V <sub>CC</sub> = 5.5 V,	Outputs high		1.5	2		2		2		
Icc	A or B ports	$I_{O} = 0$ ,	Outputs low		32	40		40		40	mA	
		$V_I = V_{CC}$ or GND	Outputs disabled		1	2		2		2		
ΔICC¶	V <sub>CC</sub> = 5.5 V, One input at 3.4 V, Other inputs at V <sub>CC</sub> or GND				50		50		50	μΑ		
Ci	Control inputs	V <sub>I</sub> = 2.5 V or 0.5 V			3						pF	
C <sub>io</sub>	A or B ports	V <sub>O</sub> = 2.5 V or 0.5 V			9						pF	

<sup>\*</sup> On products compliant to MIL-PRF-38535, this parameter does not apply.

This is the increase in supply current for each input that is at the specified TTL voltage level rather than VCC or GND.



<sup>†</sup> All typical values are at  $V_{CC} = 5 \text{ V}$ .

<sup>‡</sup> Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

<sup>§</sup> The parameters IOZH and IOZL include the input leakage current.

# SN54ABT16853, SN74ABT16853 DUAL 8-BIT TO 9-BIT PARITY BUS TRANSCEIVERS

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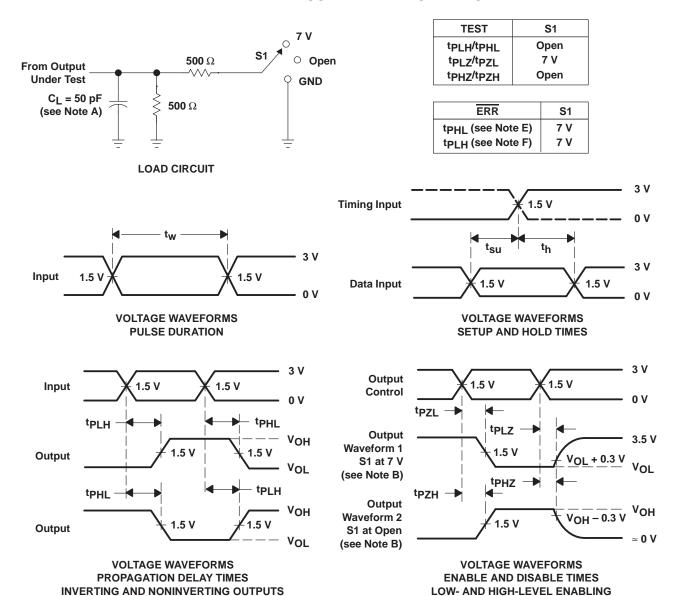
# timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

			V <sub>CC</sub> = T <sub>A</sub> = 2	: 5 V, 25°C	SN54AB	Г16853	SN74AB1	16853	UNIT	
			MIN	MAX	MIN	MAX	MIN	MAX		
	Pulse duration	LE high or low	8.5		8.5	1/5	8.5		no	
t <sub>W</sub>	Fulse duration	CLR low	4		4	9E	4		ns	
	Setup time	A, B, and PARITY before LE↓	10		10	2	10		no	
t <sub>su</sub>	Setup time	CLR before LE↓	0		9		0		ns	
<b>.</b>	Hold time	A, B, and PARITY after LE↓	0	·	0	·	0		no	
t <sub>h</sub>	Hold little	CLR after LE↓	0		Q 0		0		ns	

# switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V <sub>(</sub>	CC = 5 V 4 = 25°C	<u>',</u>	SN54AB1	Г16853	SN74AB1	16853	UNIT	
	(INFOT)	(001F01)	MIN	TYP	MAX	MIN	MAX	MIN	MAX		
<sup>t</sup> PLH	A or B	B or A	1.5	2.5	3.3	1.5	4.2	1.5	4.1	ns	
<sup>t</sup> PHL	AOIB	BOIA	2	3.1	3.9	2	4.5	2	4.3	115	
<sup>t</sup> PLH	A or OE	PARITY	2	4.6	5.9	2	7.3	2	7.1	ns	
<sup>t</sup> PHL	A or OE	FANITI	2	4.8	6.2	2	7.6	2	7.2	115	
t <sub>PLH</sub>	CLR	ERR	2	3.7	5.1	2	5.9	2	5.7	ns	
<sup>t</sup> PZH	ŌĒ	A or B	2	3.9	4.9	2	5.8	2	5.6		
t <sub>PZL</sub>	OE	AUIB	2.5	4.3	5.1	2.5	6.2	2.5	6	ns	
<sup>t</sup> PHZ	ŌĒ	A or B	2	3.6	4.5	2	5.5	2	5.4	ns	
t <sub>PLZ</sub>	OE	AOIB	1.5	3	3.8	1,5	4.7	1.5	4.3	115	
<sup>t</sup> PZH	ŌĒ	PARITY	2	3.6	5	2	5.8	2	5.7	ns	
t <sub>PZL</sub>	OE	FANITI	2.5	4.4	5.8	2.5	6.7	2.5	6.5	115	
<sup>t</sup> PHZ	ŌĒ	PARITY	1.5	3.2	4	1.5	4.8	1.5	4.7	ns	
t <sub>PLZ</sub>	OE	FANITI	1.5	2.9	3.7	1.5	4.2	1.5	4.1	115	
<sup>t</sup> PLH	Œ	<u> </u>	2	3.5	4.2	2	5	2	4.8	ns	
<sup>t</sup> PHL	LE	ERR	2	3.4	4.4	2	5.2	2	4.9	115	
<sup>t</sup> PLH	A, B, or PARITY	ERR	2	4.5	6.3	2	7.5	2	7.2	ne	
t <sub>PHL</sub>	A, D, OI PARITT	EKK	2	4.8	6.3	2	7.7	2	7.4	ns	

#### PARAMETER MEASUREMENT INFORMATION



NOTES: A. CL includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_O$  = 50  $\Omega$ ,  $t_\Gamma \leq$  2.5 ns,  $t_f \leq$  2.5 ns.
- D. The outputs are measured one at a time with one transition per measurement.
- E.  $t_{PHL}$  is measured at 1.5 V.
- F.  $t_{PLH}$  is measured at  $V_{OL}$  + 0.3 V.

Figure 1. Load Circuit and Voltage Waveforms





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#### PACKAGING INFORMATION

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
74ABT16853DGGRE4	ACTIVE	TSSOP	DGG	56	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74ABT16853DGGRG4	ACTIVE	TSSOP	DGG	56	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT16853DGGR	ACTIVE	TSSOP	DGG	56	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT16853DL	ACTIVE	SSOP	DL	56	20	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT16853DLG4	ACTIVE	SSOP	DL	56	20	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT16853DLR	ACTIVE	SSOP	DL	56	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT16853DLRG4	ACTIVE	SSOP	DL	56	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

<sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND**: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

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**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

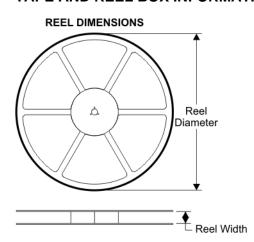
(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

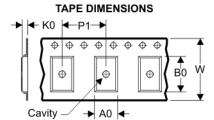
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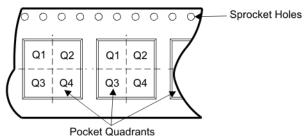
### TAPE AND REEL BOX INFORMATION





	Dimension designed to accommodate the component width
	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



Device	Package	Pins	Site	Reel Diameter (mm)	Reel Width (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ABT16853DGGR	DGG	56	SITE 41	330	24	8.6	15.6	1.8	12	24	Q1
SN74ABT16853DLR	DL	56	SITE 41	330	32	11.35	18.67	3.1	16	32	Q1





Device	Package	Pins	Site	Length (mm)	Width (mm)	Height (mm)
SN74ABT16853DGGR	DGG	56	SITE 41	346.0	346.0	0.0
SN74ABT16853DLR	DL	56	SITE 41	346.0	346.0	0.0

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RFID	www.ti-rfid.com	Telephony	www.ti.com/telephony
Low Power Wireless	www.ti.com/lpw	Video & Imaging	www.ti.com/video
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